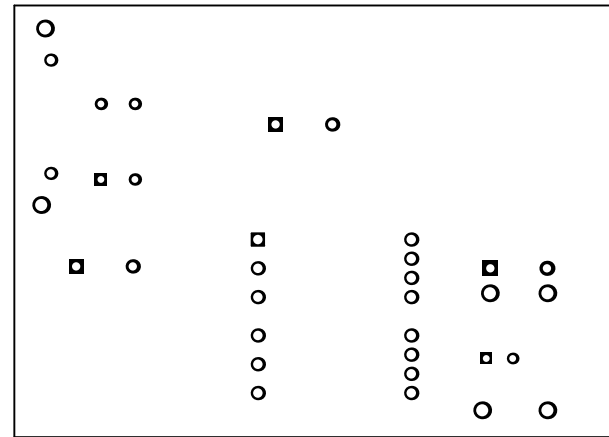
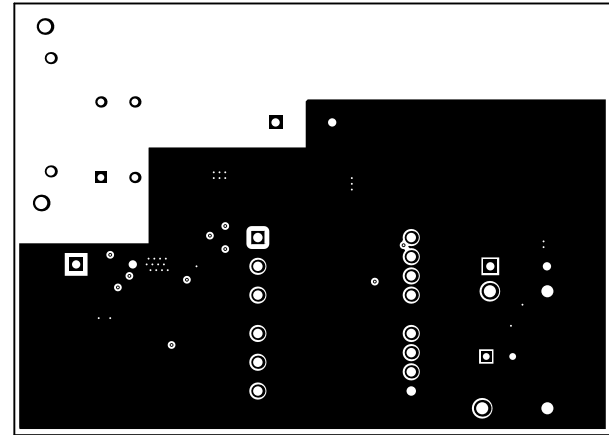


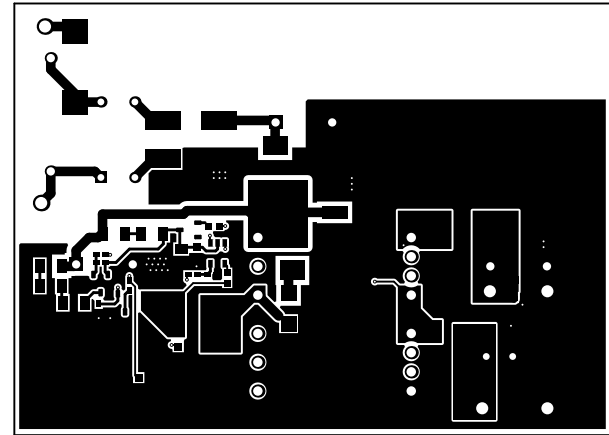
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 12/8/2016 4:06:08 PM	TEXAS INSTRUMENTS	



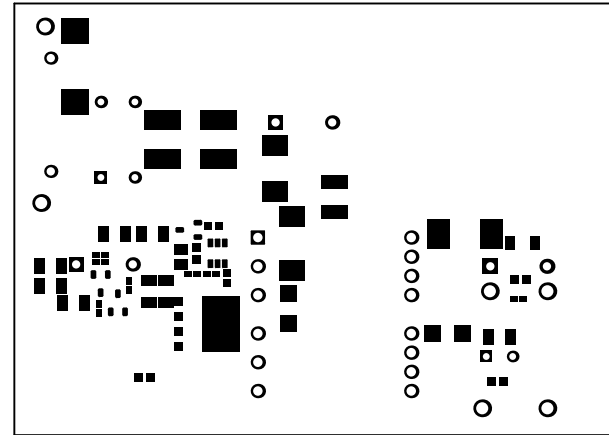
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 12/8/2016 4:06:09 PM	TEXAS INSTRUMENTS	



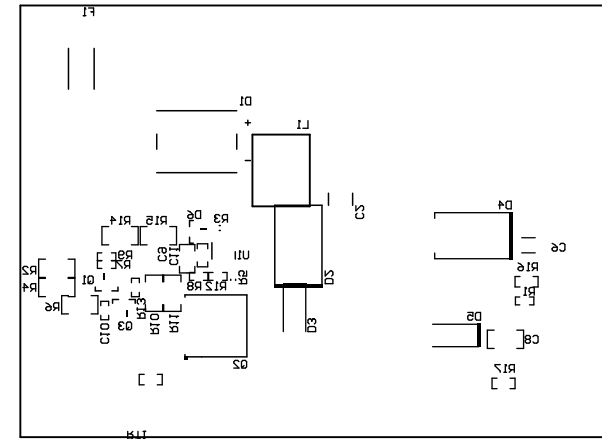
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 12/8/2016 4:06:09 PM	TEXAS INSTRUMENTS	



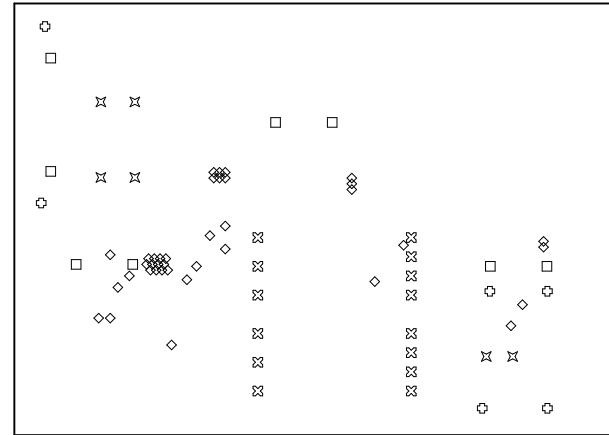
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 12/8/2016 4:06:10 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/8/2016 4:06:10 PM	TEXAS INSTRUMENTS	

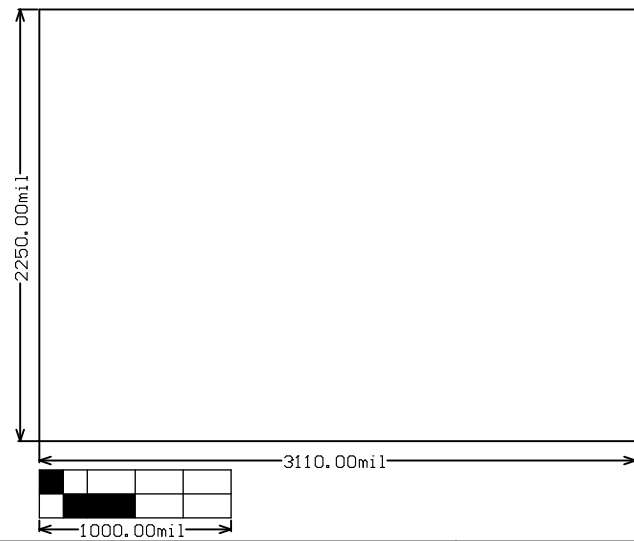


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 12/8/2016	4:06:11 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	38	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	6	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	14	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	6	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	72 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 12/8/2016	4:06:11 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20545	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 12/8/2016 4:06:12 PM	TEXAS INSTRUMENTS	

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